

TRISIL[™]

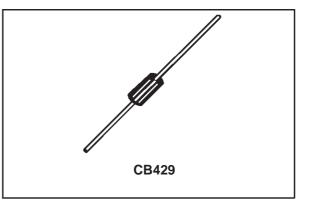
FEATURES

- BIDIRECTIONAL CROWBAR PROTECTION.
- VOLTAGE RANGE: FROM 62 V TO 270 V.
- HOLDING CURRENT: $I_{H} = 150 \text{mA min.}$
- REPETITIVE PEAK PULSE CURRENT : IPP = 100 A, 10/1000 µs.
- UL RECOGNIZED FILE # E136224

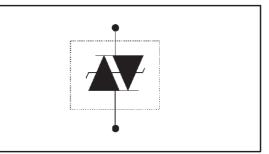
DESCRIPTION

The TPB series are TRISIL devices especially designed for protecting sensitive telecommunication equipment against lightning and transient voltages induced by AC power lines. They are available in the CB429 axial package.

TRISIL devices provide bidirectional protection by crowbar action. Their characteristic response to transient overvoltages makes them particularly suited to protect voltage sensitive telecommunication equipment.



SCHEMATIC DIAGRAM



COMPLIES WITH THE FOLLOWING STANDARDS:	Peak Surge Voltage (V)	Voltage Waveform (μs)	Current Waveform (μs)	Admissible Ipp (A)	Necessary Resistor (Ω)
CCITT K20	4000	10/700	5/310	100	-
VDE0433	4000	10/700	5/310	100	-
VDE0878	4000	1.2/50	1/20	100	-
IEC-1000-4-5	level 4 level 4	10/700 1.2/50	5/310 8/20	100 100	-
FCC Part 68, lightning surge type A	1500 800	10/160 10/560	10/160 10/560	200 100	-
FCC Part 68, lightning surge type B	100	5/320	5/320	25	-
BELLCORE TR-NWT-001089 First level	2500 1000	2/10 10/1000	2/10 10/1000	500 100	-
BELLCORE TR-NWT-001089 Second level	500	2/10	2/10	500	-
CNET 131-24	4000	0.5/700	0.8/310	100	-

ABSOLUTE MAXIMUM RATINGS (Tamb = 25°C)

Symbol	Parameter	Value	Unit	
Р	Power dissipation on infinite heatsink	5	W	
IPP	Peak pulse current	10/1000 μs 8/20 μs 2/10 μs	100 150 500	A
ITSM	Non repetitive surge peak on-state current	50	А	
l ² t	l ² t value for fusing tp = 20 ms		25	A ² s
dV/dt	Critical rate of rise of off-state voltage V _{RM}		5	kV/μs
T _{stg} T _j	Storage temperature range Maximum junction temperature	- 55 to + 150 150	သိ သိ	
TL	Maximum lead temperature for soldering during case	230	°C	

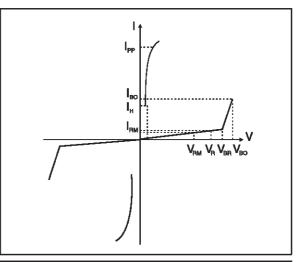
THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-l)	Junction to leads (L _{lead} = 10mm)	20	°C/W
R _{th} (j-a)	Junction to ambient on printed circuit (L _{lead} = 10 mm)	75	°C/W

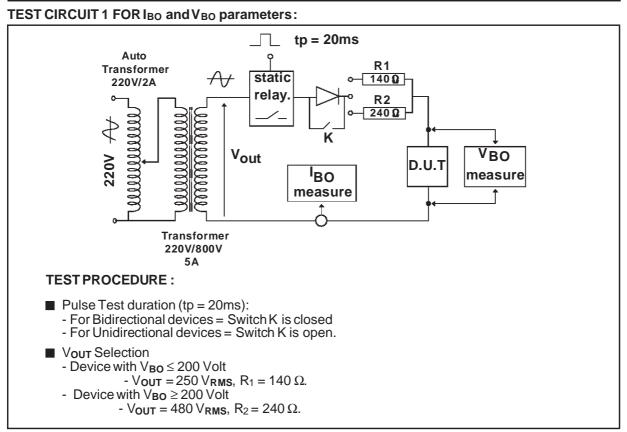
ELECTRICAL CHARACTERISTICS

 $(T_{amb} = 25^{\circ}C)$

Symbol	Parameter					
Vrm	Stand-off voltage					
Irm	Leakage current at stand-off voltage					
VR	Continuous Reverse voltage					
V _{BR}	Breakdown voltage					
V _{BO}	Breakovervoltage					
Iн	Holding current					
IBO	Breakovercurrent					
I _{PP}	Peak pulse current					
С	Capacitance					



Туре	I _{RM} @ V _{RM} max.		I _R @ V _R max. note1		V _{BO} @ I _{BO} max. note2		I н min. note3	C max. note4
	μΑ	V	μΑ	V	v	mA	mA	рF
TPB62	2	56	50	62	82	800	150	300
TPB68	2	61	50	68	90	800	150	300
TPB100	2	90	50	100	133	800	150	200
TPB120	2	108	50	120	160	800	150	200
TPB130	2	117	50	130	173	800	150	200
TPB180	2	162	50	180	240	800	150	200
TPB200	2	180	50	200	267	800	150	200
TPB220	2	198	50	220	293	800	150	200
TPB240	2	216	50	240	320	800	150	200
TPB270	2	243	50	270	360	800	150	200
Note 1:IR measured at VR guarantees VBRmin \geq VRNote 2:Measured at 50 Hz (1 cycle) - See test circuit 1.Note 3:See test circuit 2.Note 4:VR = 1V, F = 1MHz, refer to fig.3 for C versus VR2/5								



TEST CIRCUIT 2 for I_H parameter

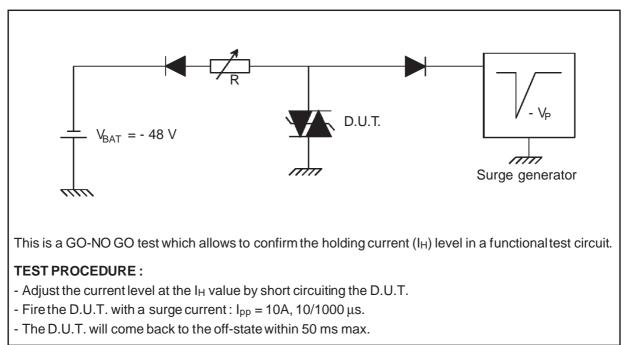




Fig. 1: Non repetitive surge peak on-state current versus overload duration (Tj initial=25°C).

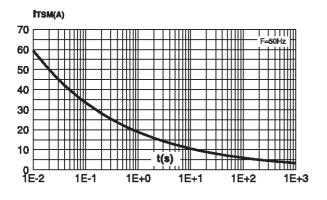


Fig. 3: Relative variation of junction capacitance versus reverse applied voltage(typical values). Note: For V_{RM} upper than 56V, the curve is extrapolated(dotted line).

Fig. 2: Relative variation of holding current versus junction temperature.

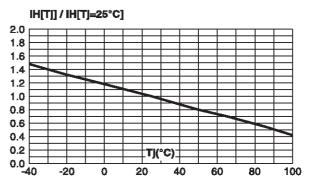


Fig. 4: On-state current versus on-state voltage (typical values).

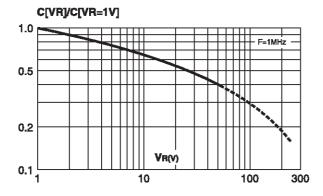
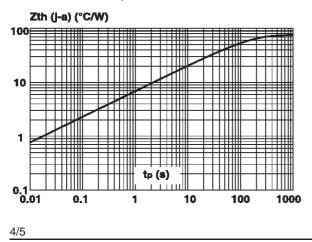
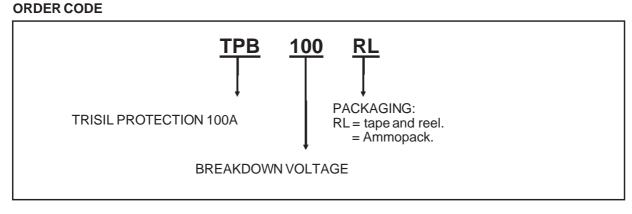


Fig. 5: Transient thermal impedance junction to ambient versus pulse duration (for FR4 PC Board with $T_{Lead} = 10$ mm).



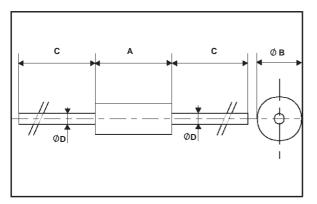
IT(A) VT(v)



MARKING : Logo, Date Code, Part Number.

PACKAGE MECHANICAL DATA.

CB429 Plastic



	DIMENSIONS							
REF.	Mi	llimete	limeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.		
Α	9.45	9.50	9.80	0.372	0.374	0.386		
В	26			1.024				
ØC	4.90	5.00	5.10	0.193	0.197	0.201		
ØD	0.94	1.00	1.06	0.037	0.039	0.042		
L1			1.27			0.050		
note	note 1 : the lead is not controlled in zone L_1							

Packaging: Standard packaging is in tape and reel.

Weight: 0.85g

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